100 Lead Metric Quad Flat Pack (MQFP) Package Dimensions



SEMICONDUCTOR IM

100 Lead Metric Quad Flat Pack (MQFP) 3.2mm Footprint



Pin 1 Indentifier

E1

Е

В

Symbol	Inches		Millimeters		Natas
	Min.	Max.	Min.	Max.	Notes
А	_	.134	_	3.40	
A1	.010	.020	.25	_	
A2	.098	.114	2.50	2.90	
В	.008	.016	.22	.40	3, 5
С	.004	.009	.11	.23	5
D	.913 BSC		23.20 BSC		
D1	.787 BSC		20.00 BSC		
E	.677 BSC		17.20 BSC		
E1	.551 BSC		14.00 BSC		
е	.0256 BSC		.65 BSC		
L	.028	.040	.73	1.03	4
Ν	100		100		
ND	30		30		
NE	20		20		
α	0°	7 °	0°	7 °	
CCC	—	.004	_	.12	

Notes:

- 1. All dimensions and tolerances conform to ANSI Y14.5M-1982.
- 2. Controlling dimension is millimeters.
- Dimension "B" does not include dambar protrusion. Allowable dambar protrusion shall be .08mm (.003in.) maximum in excess of the "B" dimension. Dambar cannot be located on the lower radius or the foot.
- 4. "L" is the length of terminal for soldering to a substrate.
- 5. "B" & "C" includes lead finish thickness.



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